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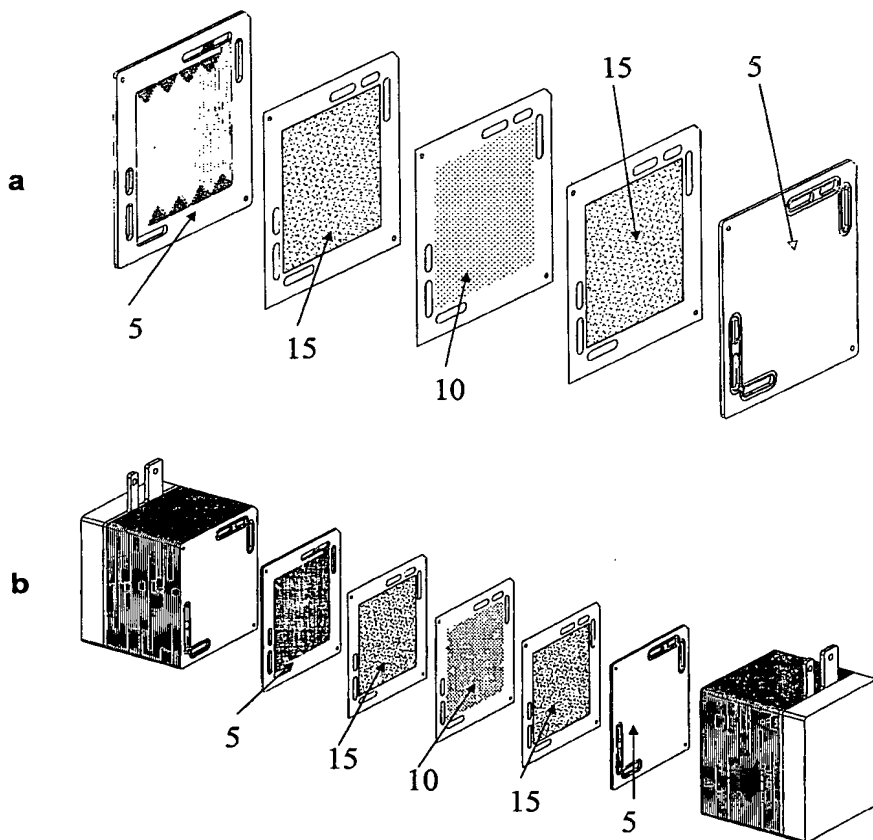
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(54) Title: ELECTROCHEMICAL CELL COMPONENT



(57) Abstract: An electroconductive integrated substrate and a process of producing the same, which comprises a porous conductive gas diffusion layer having large number of pores with significant gas permeability, and a gas impermeable electroconductive flow field plate having landing surfaces laminated on the surface of gas diffusion layer and integrally bonded to thereto by the molten composite from the landing surface. There is provided a process for joining the gas diffusion layer to a flow field plate in an electrochemical cell. The process comprises the step of welding the landing surface of the flow field plate to the gas diffusion layer using resistance welding.

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